Cleaning Wafer Substrates

Cleaning Substrate Surfaces

There are many methods for cleaning substrate materials; much depends on the intended application as well as the level of cleanliness desired. Here are a couple of suggestions.

One common method is to place the wafer in acetone and use an ultrasonic cleaner for some period of time (typically 5 to 15 minutes). Immediately after removal, rinse with ethanol and/or methanol and dried with a dry N2 gun, or a compressed air can. When using this method, you must watch for residue left on the surface by the solvents - this can be an issue.

For many surface, the use of the Plasma Prep III will easily remove organics in an O2 environment. Other gasses can be used for different cleaning applications.

For spin-coating applications, adding a few drops of a strong solvent (such as 2-methoxyethanol) onto the wafer using a syringe. Then spin the wafer to remove the excess solvent, followed by drying on a hot plate to remove any remaining organics.

Do you have a favorite method? Please let us know and we will acknowledge and add you to our suggested preparations!